



SOCKET NO.: TALW-0180

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PATENT

AMENDMENT MAR 12 2003

TC 1700 MAIL ROOM

**In the Specification:**

Please replace the paragraph beginning at line 18 of page 6 with the following rewritten paragraph:

91 --The technique filling up microvia holes with pulse reverse electrolytic plating is recited, for example, in "Gist of the 100th Lecture" (held on October 6 and 7, 1999) by Surface Finishing Society of Japan.--

Please replace the paragraph beginning at line 3 of page 20 with the following rewritten paragraph:

92 -- A plating bath which accommodates an insoluble anode and a printed-circuit board, and a copper dissolved bath which supplies copper ions are arranged. The insoluble anode is arranged as opposed to the printed-circuit board being a cathode, and a forward/reverse current is applied between both of the electrodes. Iron ions are added to a plating solution.--

**In the Claims:**

Please amend the claims to read:

- 93
1. (Amended) An electrolytic plating method, comprising:  
using a wiring board as one pole, and an insoluble electrode as the other pole;  
and  
performing electrolytic plating by applying a forward/reverse current with the use of a metal plating solution which includes iron ions by 0.1 gram/liter or more and is stirred to move parallel to the wiring board surface on which a plating layer is generated so that microvia holes on the wiring board are filled up with metal plating.